



Solid State Equipment Corporation

www.ssecusa.com

Corporate Office:

185 Gibraltar Road  
Horsham, PA 19044  
215-328-0700  
Fax: 215-328-9410

Branch Offices:

Im Gewerbepark C-25  
93059 Regensburg, Germany  
49 (0) 941-46-36-115  
Fax: 49 (0) 941-46-36-100

17F-1, No. 285, Sec 2  
Kuang-Fu Road  
Hsin Chu, Taiwan, R.O.C.  
(886) 3-516-3235  
Fax: (886) 3-516-3236

Rm 203, Spottiswoode Garden  
1415 Huashan Road  
Shanghai, P.R.C. 200052  
(86) 21-5258-3909  
Fax: (86) 21-6282-9036

## **FOR IMMEDIATE RELEASE**

### **Multi-wafer Size, Single Side Wet Etch Spindle Tooling**

**Horsham, PA**— Highest equipment utilization with multiple size wafers for processes that require single side, single wafer wet etching is now available for applications including wafer thinning, backside stripping, UBM etch, photoresist strip and many others.

SSEC's wafer automation enables PC recipe selection of wafer size without hardware changes to spindle tooling or robotics, enabling size change by wafer lot.

Solid State Equipment Corporation is a 43 year veteran manufacturer of single wafer wet cleaners and processors from its headquarters in suburban Philadelphia. SSEC maintains worldwide sales and technical service offices in Horsham, Pennsylvania; San Jose, California; Regensburg, Germany; Cramlington, England; Taiwan, R.O.C.; Shanghai, P.R.C; Woodlands, Singapore; Gyeonggi, R.O.K.; and Laguna, Philippines.

Solid State Equipment Corporation  
Horsham, PA  
215-328-0700  
www.ssecusa.com  
[info@ssecusa.com](mailto:info@ssecusa.com)

